



BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

Brighten up The World With LED!



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

PRODUCT DATASHEET

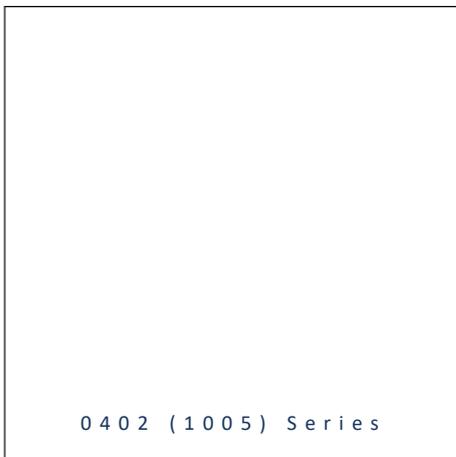


- ▶ PCB / CHIP LED
- ▶ 0402 (1005) 0.48t
- ▶ Sky White (9700K)

NOW58S18-5MA



Release Date: 25 October 2021 Version: A1.2



0402 (1005) Series

RoHS
Compliant



FEATURES:

- **Package:** PCB / CHIP White SMT Package
- **Forward Current:** 5mA
- **Forward Voltage (typ.):** 2.8V
- **Luminous Intensity (typ.):** 190mcd@5mA
- **Colour:** Sky White
- **CCT (typ.):** 9700K
- **Viewing angle:** 120°
- **Materials:**
 - Die: InGaN
 - Resin: Epoxy (Yellow Diffused)
- **Operating Temperature:** -40~+85°C
- **Storage Temperature:** -40~+100°C
- **ESD:** 500V
- **Grouping parameters:**
 - Forward voltage
 - Luminous intensity
 - CIE Chromaticity
- **Soldering methods:** IR Reflow soldering; wave soldering
- **Preconditioning:** acc. to JEDEC Level 3
- **Packing:** 8mm tape with max.3000/reel, ø180mm (7")

APPLICATIONS:

- LCD Backlighting
- Indication Light
- 3C Consumer Goods
- Keyboard Light

CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

| Parameter | Symbol | Ratings | Unit |
|--------------------------------------|------------------|----------|------|
| Forward Current | I _F | 10 | mA |
| Peak Forward Current Duty 1/10@10KHz | I _{FP} | 100 | mA |
| Reverse Current @5V | I _R | 50 | μA |
| Power Dissipation | P _D | 31 | mW |
| Electrostatic Discharge | ESD | 500 | V |
| Operating Temperature | T _{OPR} | -40~+85 | °C |
| Storage Temperature | T _{STG} | -40~+100 | °C |

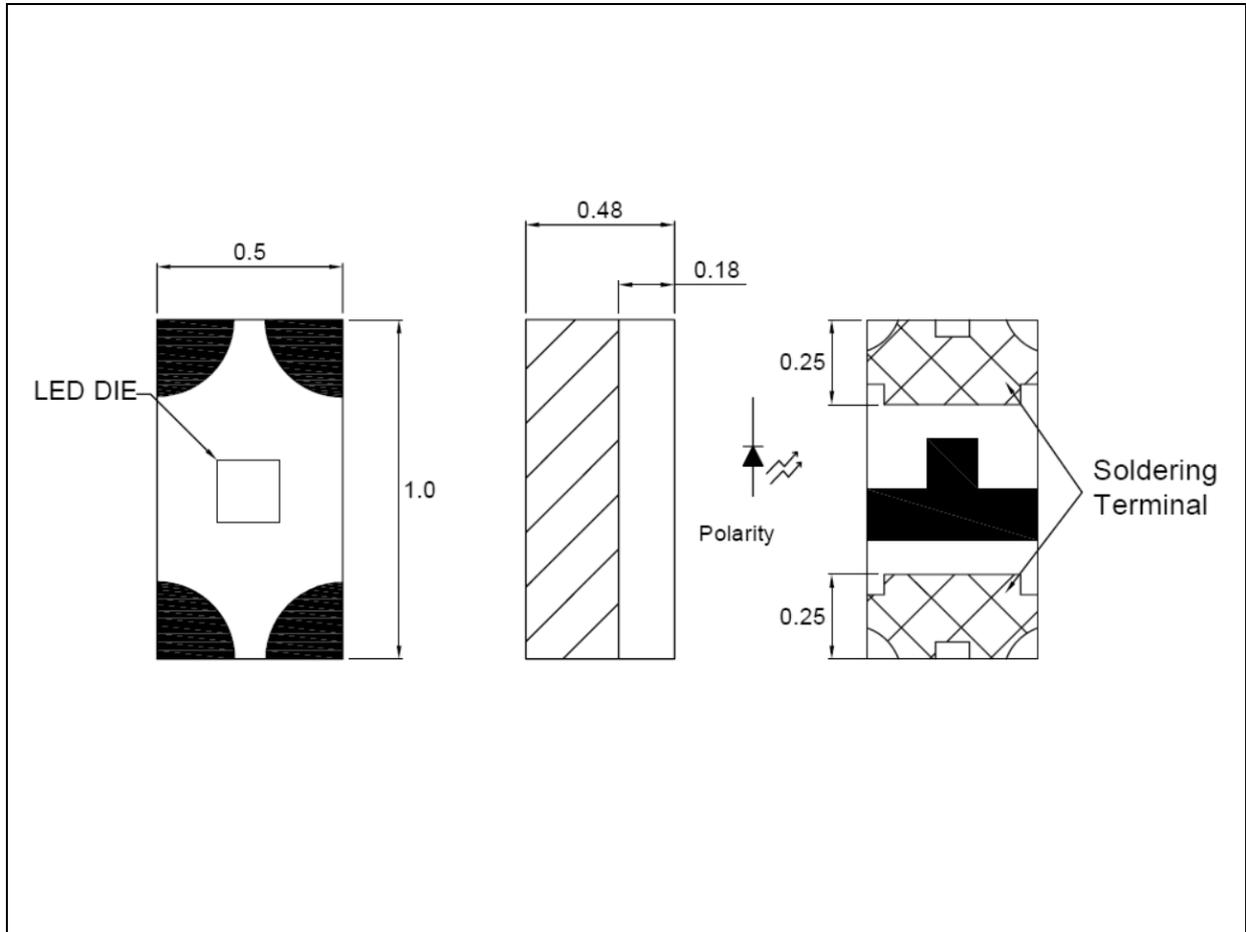
Electrical & Optical Characteristics (Ta=25°C)

| Parameter | Symbol | Values | | | Unit | Test Condition |
|--------------------------|-------------------|--------|------|--------|------|---------------------|
| | | Min. | Typ. | Max. | | |
| Forward Voltage | V _F | 2.5 | --- | 3.1 | V | I _F =5mA |
| Luminous Intensity | I _v | 125 | 190 | --- | mcd | I _F =5mA |
| Chromaticity Coordinates | X | 0.2900 | --- | 0.3100 | --- | I _F =5mA |
| | Y | 0.2250 | --- | 0.3400 | | |
| Colour Temperature | CCT | --- | 9700 | --- | K | I _F =5mA |
| Viewing Angle | 2θ _{1/2} | --- | 120 | --- | deg | I _F =5mA |

1. Luminous intensity (I_v) ±15%, Forward Voltage (V_F) ±0.1V, Viewing angle(2θ_{1/2}) ±5%, CRI ±3

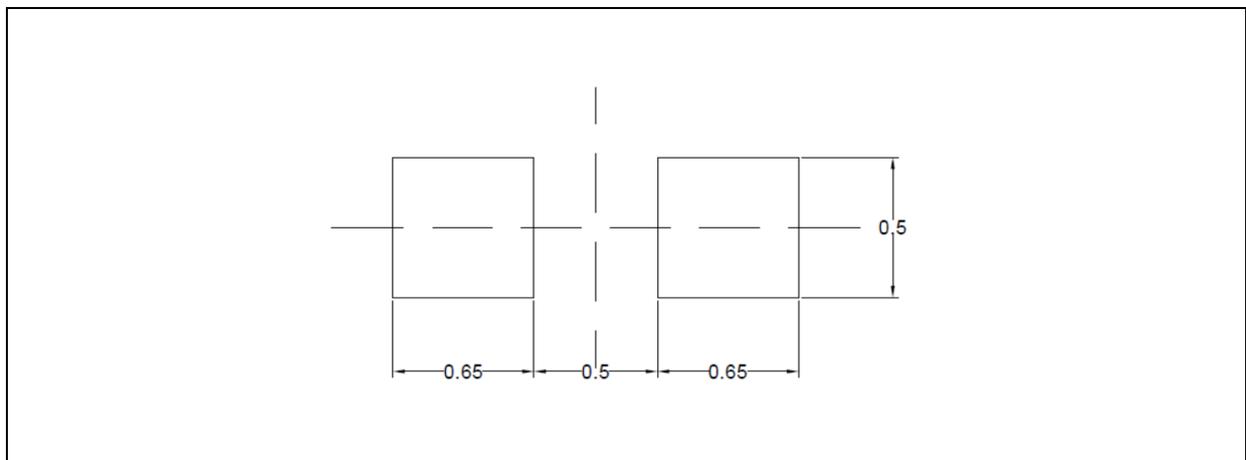
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance $\pm 0.1\text{mm}$, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance $\pm 0.1\text{mm}$ with angle tolerance $\pm 0.5^\circ$.

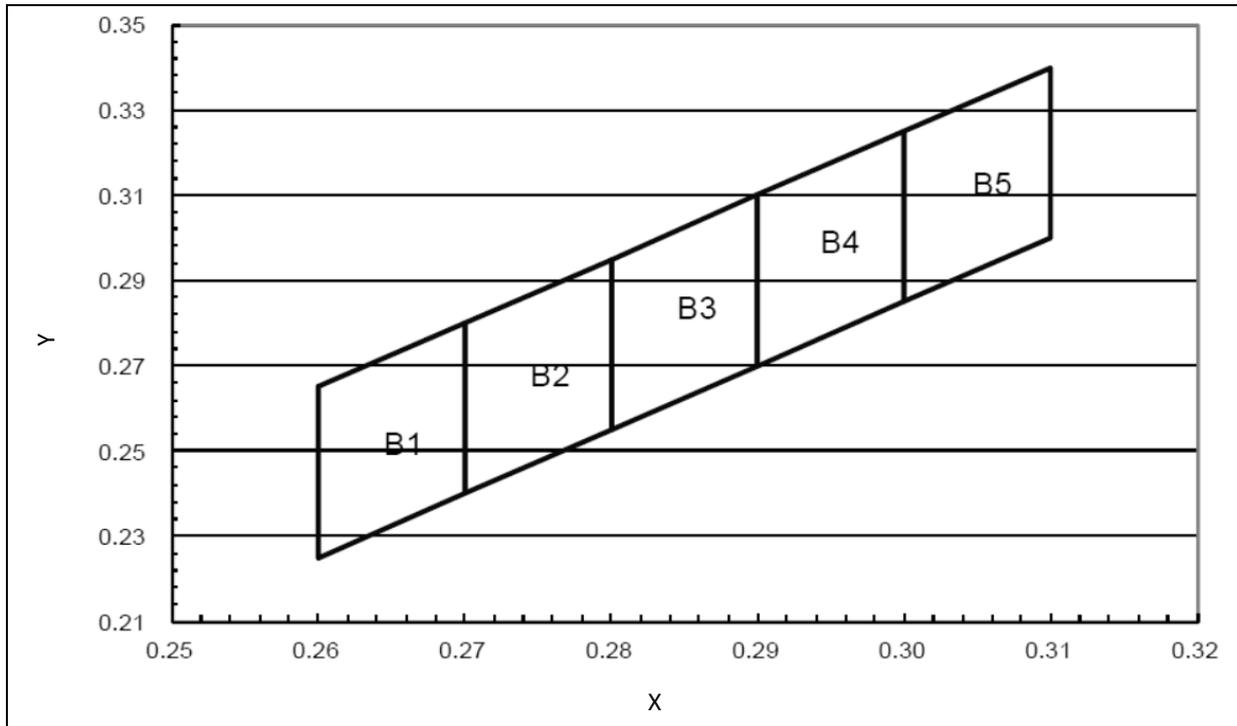
BINNING GROUPS:

 Forward Voltage Classifications ($I_F = 5\text{mA}$):

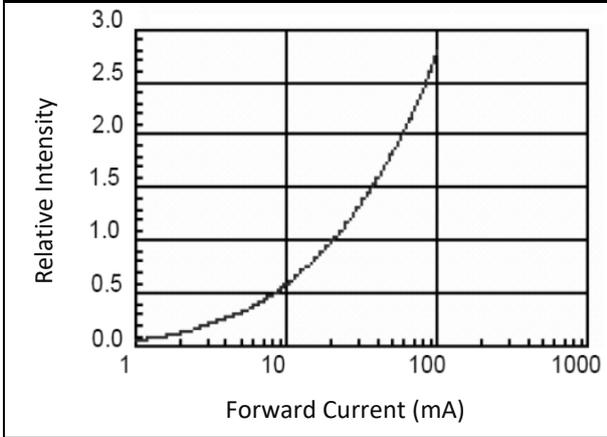
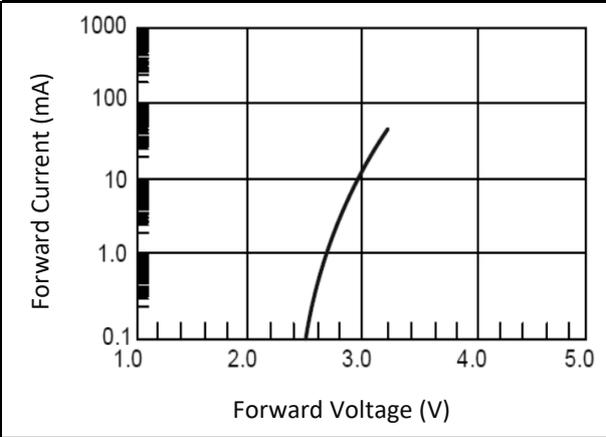
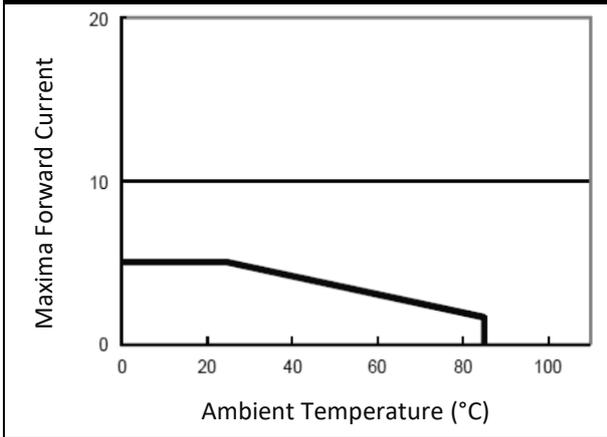
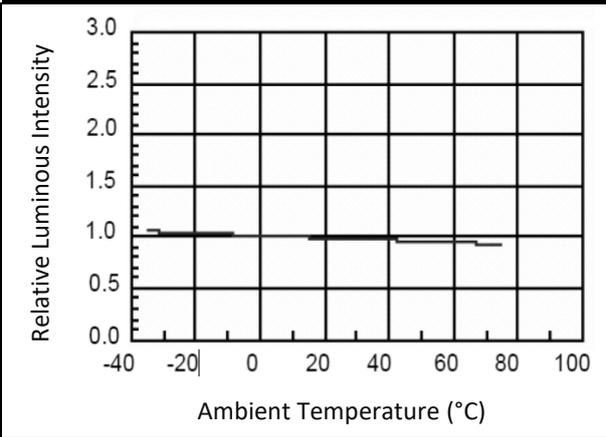
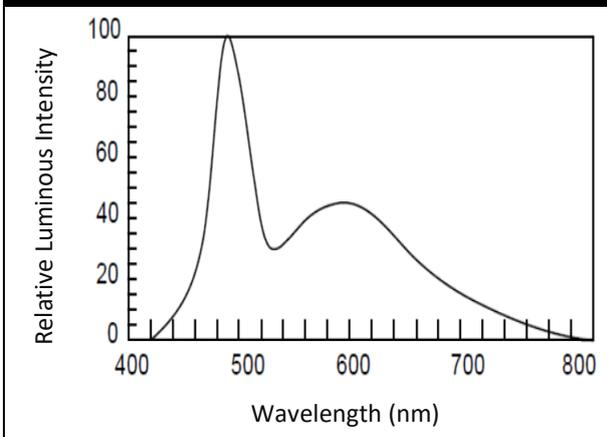
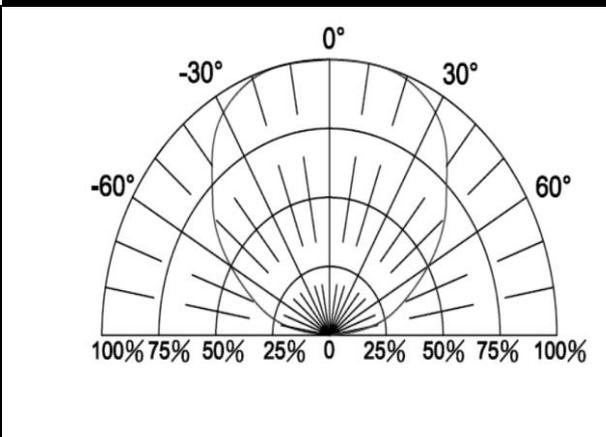
| Code | Min. | Max. | Unit |
|------|------|------|------|
| 1 | 2.5 | 2.6 | V |
| 2 | 2.6 | 2.7 | |
| 3 | 2.7 | 2.8 | |
| 4 | 2.8 | 2.9 | |
| 5 | 2.9 | 3.0 | |
| 6 | 3.0 | 3.1 | |

 Luminous Intensity Classifications ($I_F = 5\text{mA}$):

| Code | Min. | Max. | Unit |
|------|------|------|------|
| R | 125 | 200 | mcd |
| S | 200 | 320 | |
| T | 320 | 500 | |

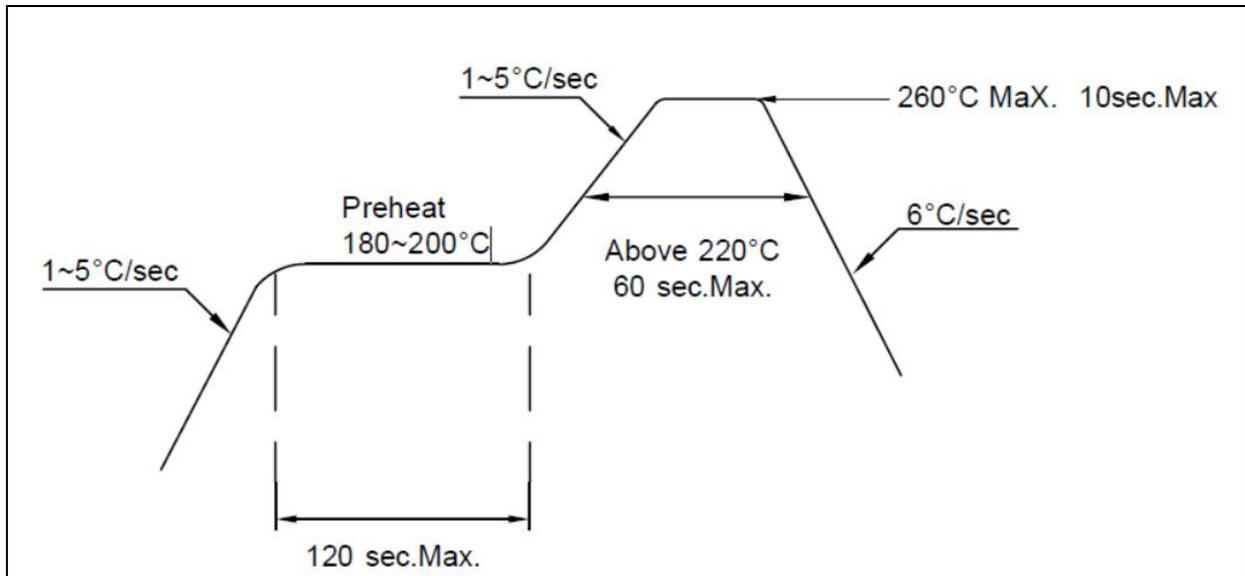
CIE CHROMATICITY DIAGRAM:

 Chromaticity Coordinates Classifications ($I_F = 5\text{mA}$):

| | 1 | | 2 | | 3 | | 4 | |
|----|--------|--------|--------|--------|--------|--------|--------|--------|
| | X | Y | X | Y | X | Y | X | Y |
| B1 | 0.2600 | 0.2650 | 0.2600 | 0.2250 | 0.2700 | 0.2400 | 0.2700 | 0.2800 |
| B2 | 0.2700 | 0.2800 | 0.2700 | 0.2400 | 0.2800 | 0.2550 | 0.2800 | 0.2950 |
| B3 | 0.2800 | 0.2950 | 0.2800 | 0.2550 | 0.2900 | 0.2700 | 0.2900 | 0.3100 |
| B4 | 0.2900 | 0.3100 | 0.2900 | 0.2700 | 0.3000 | 0.2850 | 0.3000 | 0.3250 |
| B5 | 0.3000 | 0.3250 | 0.3000 | 0.2850 | 0.3100 | 0.3000 | 0.3100 | 0.3400 |

ELECTRO-OPTICAL CHARACTERISTICS:
Relative Intensity v.s. Forward Current

Forward Current v.s. Forward Voltage

Forward Current v.s. Temperature

Luminous Intensity v.s. Temperature

Luminous Spectrum

Directive Radiation


RECOMMENDED SOLDERING PROFILE:

Lead-free Solder:

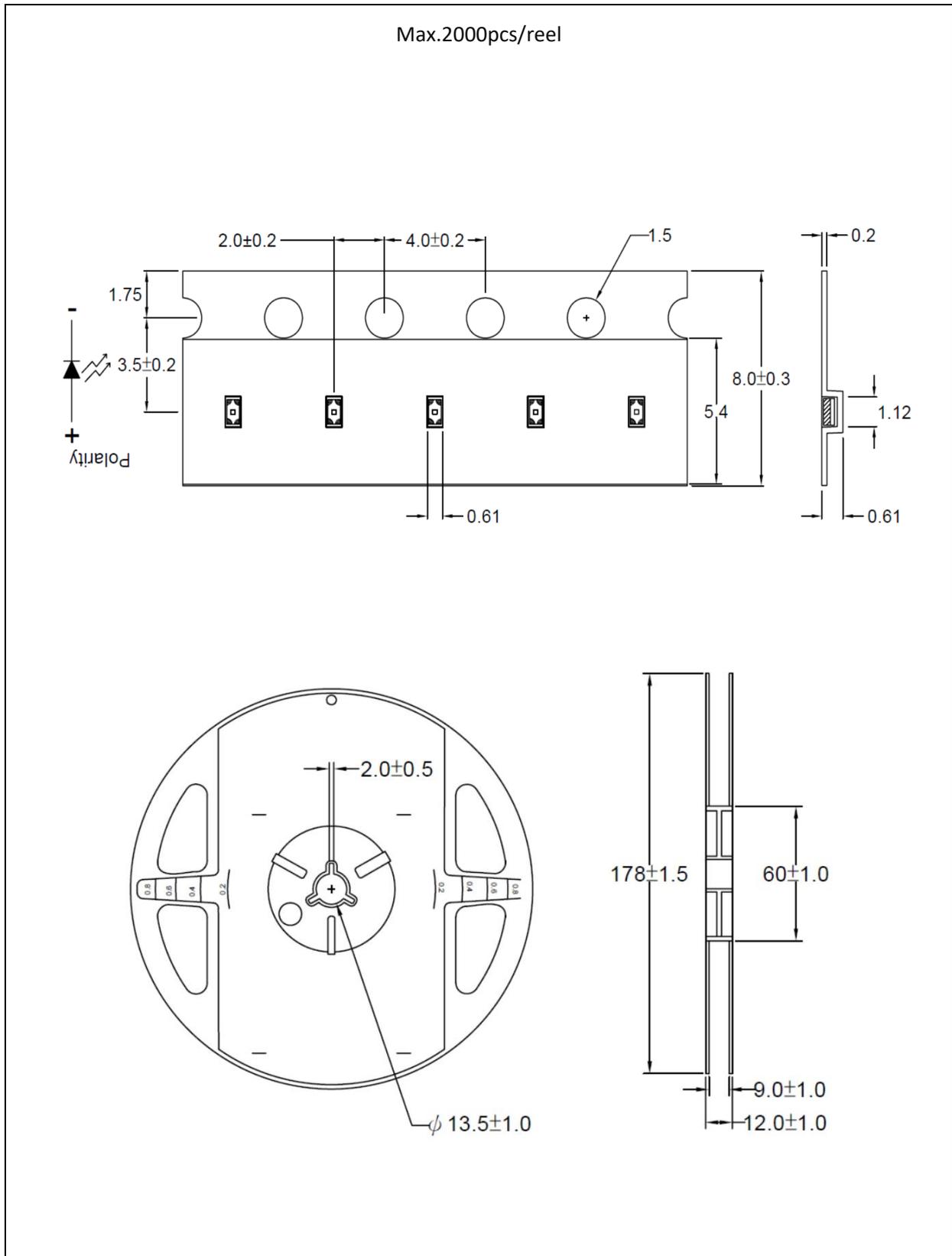


Note:

1. Maximum reflow soldering: 2 times.
2. Maximum soldering temperature should be limited to 260°C.
3. Before, during, and after soldering, should not apply stress on the components and PCB board.

PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent <10% R.H. and apply baking before use.

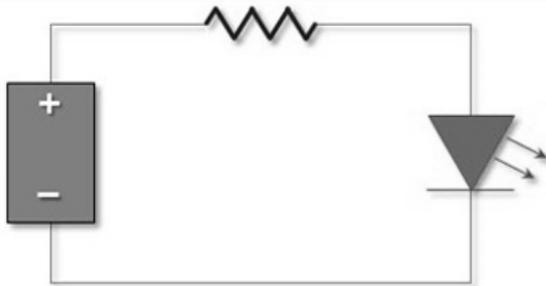
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±3°C x 72hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

REVISION RECORD:

| Version | Date | Summary of Revision |
|---------|------------|---|
| A1.0 | 20/07/2020 | Datasheet set-up. |
| A1.1 | 16/07/2021 | New datasheet format. |
| A1.2 | 25/10/2021 | Revise baking hours and packing quantity. |